

General Description

- Latest Advanced Trench Technology
- Low $R_{DS(ON)}$
- High Current Capability
- RoHS and Halogen-Free Compliant

Applications

- Notebook AC-in Load Switch
- Battery Protection Charge/Discharge

Product Summary

P-Channel

$V_{DS} = -30V$
 $I_D = -5.7A$ ($V_{GS} = -10V$)
 $R_{DS(ON)} < 32m\Omega$ ($V_{GS} = -10V$)
 $< 55m\Omega$ ($V_{GS} = -4.5V$)

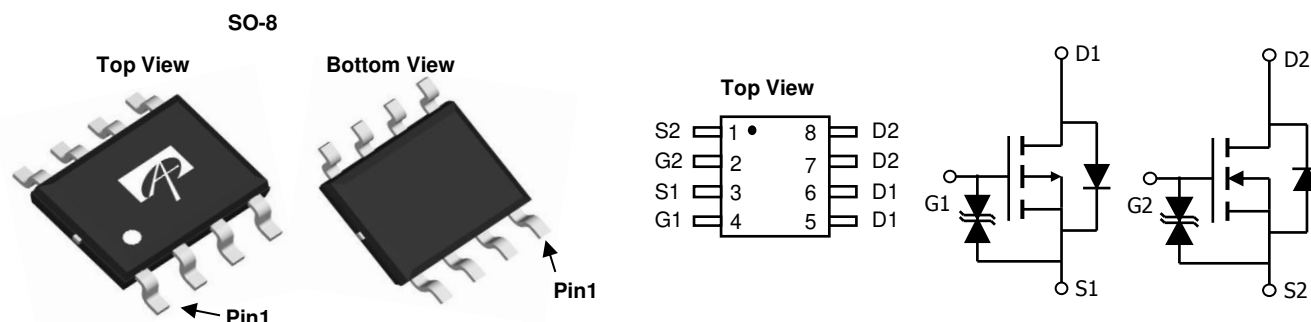
N-Channel

$V_{DS} = 30V$
 $I_D = 7A$ ($V_{GS} = 10V$)
 $R_{DS(ON)} < 20m\Omega$ ($V_{GS} = 10V$)
 $< 26m\Omega$ ($V_{GS} = 4.5V$)

ESD protection

100% UIS Tested
 100% R_g Tested

100% UIS Tested
 100% R_g Tested



Orderable Part Number	Package Type	Form	Minimum Order Quantity
AOSD26313C	SO-8	Tape & Reel	3000

Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Max Q1	Max Q2	Units	
Drain-Source Voltage	V_{DS}	-30	30	V	
Gate-Source Voltage	V_{GS}	± 20	± 20	V	
Continuous Drain Current	I_D	$T_A=25^\circ C$	-5.7	7	A
		$T_A=70^\circ C$	-4.4	5.4	
Pulsed Drain Current ^C	I_{DM}	-23	34	A	
Avalanche Current ^C	I_{AS}	20	15	A	
Avalanche energy $L=0.1mH$ ^C	E_{AS}	20	11	mJ	
Power Dissipation ^B	P_D	$T_A=25^\circ C$	1.7	1.7	W
		$T_A=70^\circ C$	1.1	1.1	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150		$^\circ C$	

Thermal Characteristics

Parameter	Symbol	Typ Q1	Max Q1	Typ Q2	Max Q2	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	52	70	52	70	$^\circ C/W$
Maximum Junction-to-Ambient ^{A D}						
Maximum Junction-to-Lead	$R_{\theta JL}$	35	45	35	45	$^\circ C/W$

P-CH Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =-250μA, V _{GS} =0V	-30			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-30V, V _{GS} =0V T _J =55°C			-1 -5	μA
advanced	Gate-Body leakage current	V _{DS} =0V, V _{GS} =±20V			±10	μA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA	-1.2	-1.7	-2.2	V
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =-10V, I _D =-5.7A T _J =125°C		25 32	32 41	mΩ
		V _{GS} =-4.5V, I _D =-4.4A		35	55	mΩ
g _{FS}	Forward Transconductance	V _{DS} =-5V, I _D =-5.7A		17		S
V _{SD}	Diode Forward Voltage	I _S =-1A, V _{GS} =0V		-0.8	-1	V
I _S	Maximum Body-Diode Continuous Current				-2	A
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =-15V, f=1MHz		1100		pF
C _{oss}	Output Capacitance			120		pF
C _{rss}	Reverse Transfer Capacitance			105		pF
R _g	Gate resistance	f=1MHz		11	18	Ω
SWITCHING PARAMETERS						
Q _{g(10V)}	Total Gate Charge	V _{GS} =-10V, V _{DS} =-15V, I _D =-5.7A		22	33	nC
Q _{g(4.5V)}	Total Gate Charge			11	18	nC
Q _{gs}	Gate Source Charge			2.5		nC
Q _{gd}	Gate Drain Charge			6.5		nC
t _{D(on)}	Turn-On DelayTime	V _{GS} =-10V, V _{DS} =-15V, R _L =2.63Ω, R _{GEN} =3Ω		12		ns
t _r	Turn-On Rise Time			9		ns
t _{D(off)}	Turn-Off DelayTime			55		ns
t _f	Turn-Off Fall Time			19		ns
t _{rr}	Body Diode Reverse Recovery Time	I _F =-5.7A, di/dt=500A/μs		12		ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =-5.7A, di/dt=500A/μs		17		nC

A. The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C. The value in any given application depends on the user's specific board design.

B. The power dissipation P_D is based on T_{J(MAX)}=150° C, using ≤ 10s junction-to-ambient thermal resistance.

C. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150° C. Ratings are based on low frequency and duty cycles to keep initial T_J=25° C.

D. The R_{θJA} is the sum of the thermal impedance from junction to lead R_{θJL} and lead to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300μs pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-ambient thermal impedance which is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, assuming a maximum junction temperature of T_{J(MAX)}=150° C. The SOA curve provides a single pulse rating.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

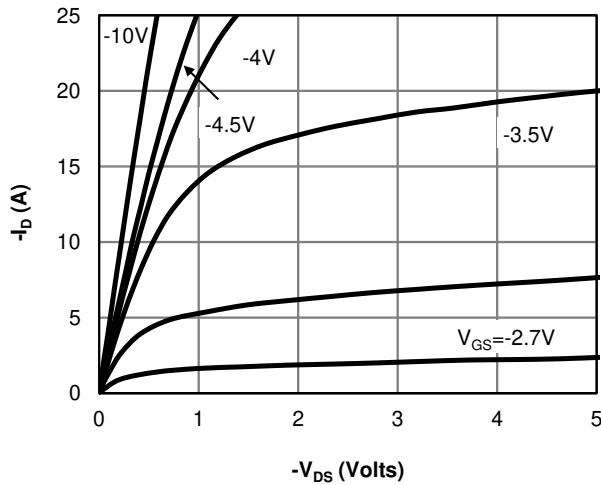


Figure 1: On-Region Characteristics (Note E)

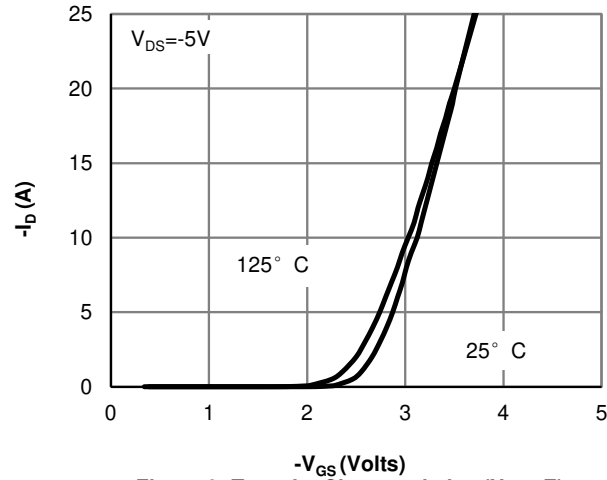


Figure 2: Transfer Characteristics (Note E)

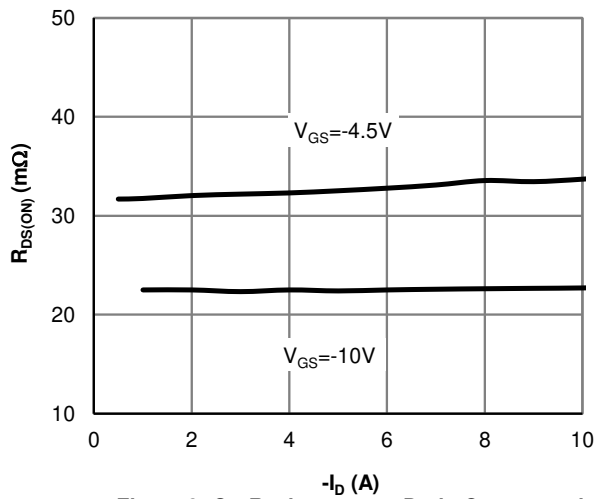


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

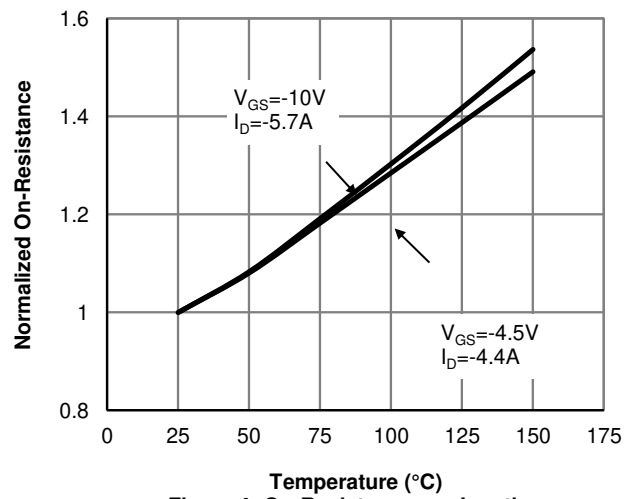


Figure 4: On-Resistance vs. Junction Temperature (Note E)

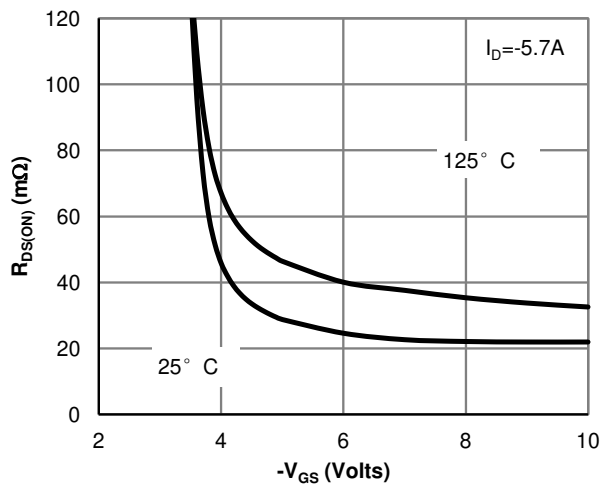


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

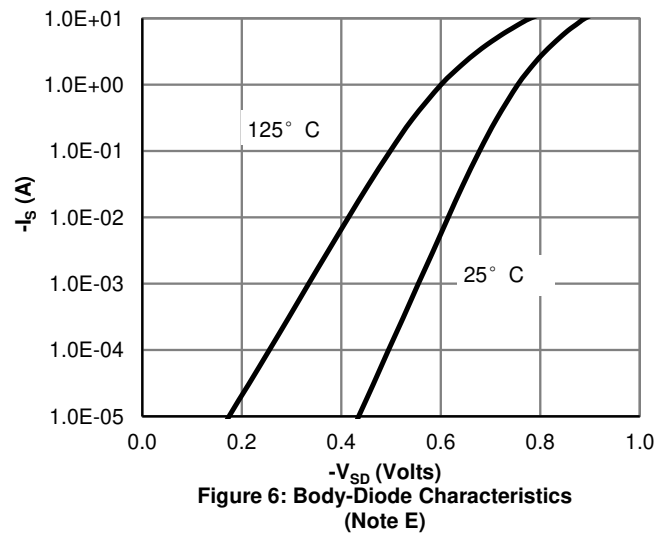


Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

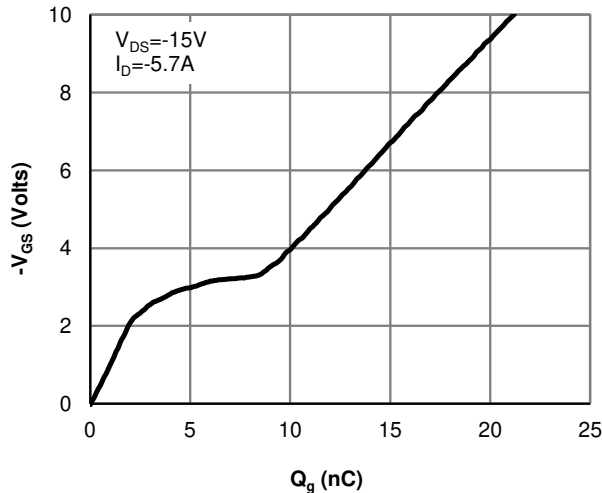


Figure 7: Gate-Charge Characteristics

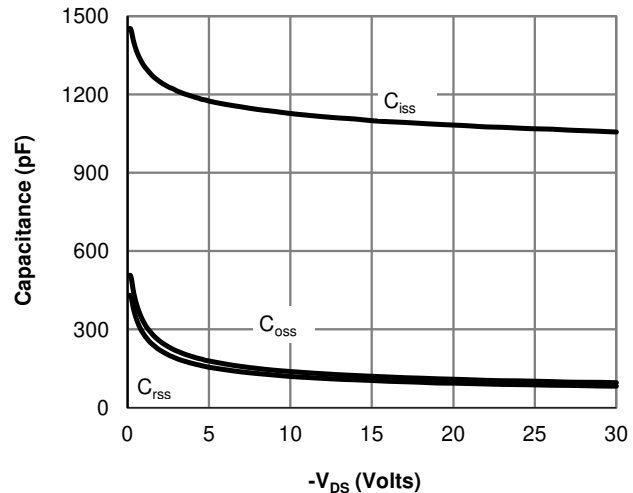


Figure 8: Capacitance Characteristics

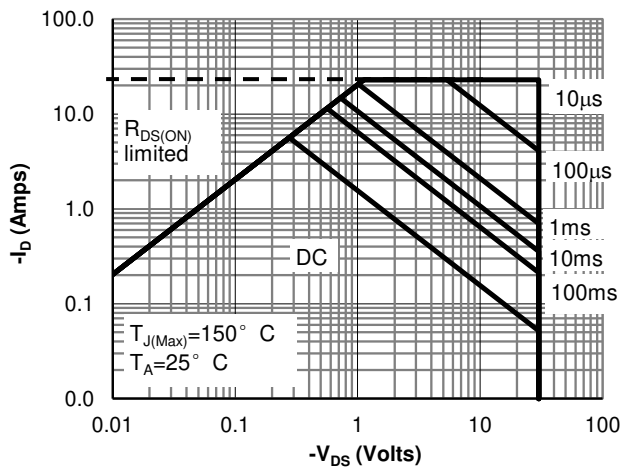


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

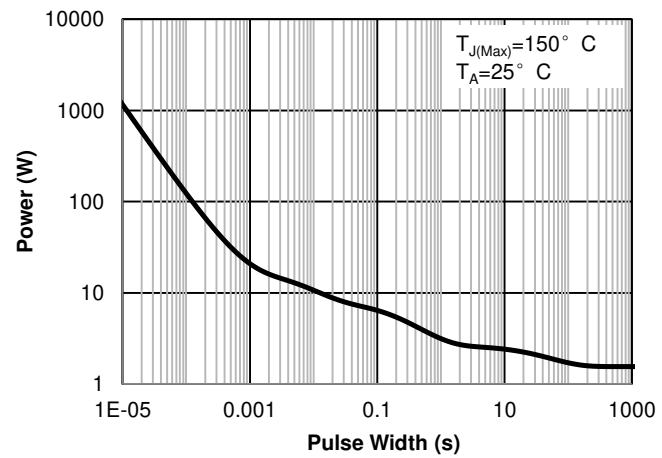


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note F)

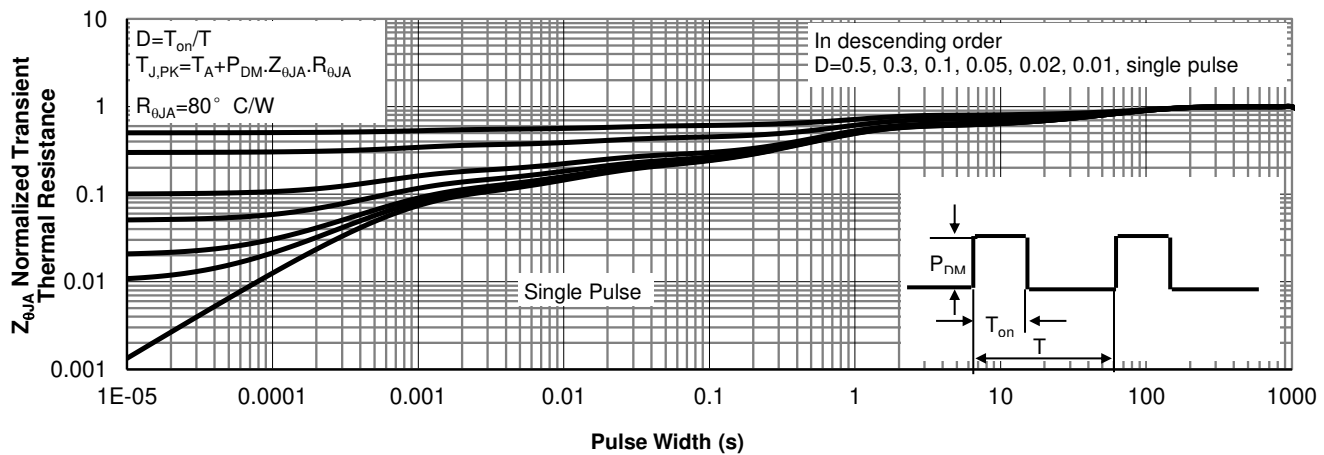
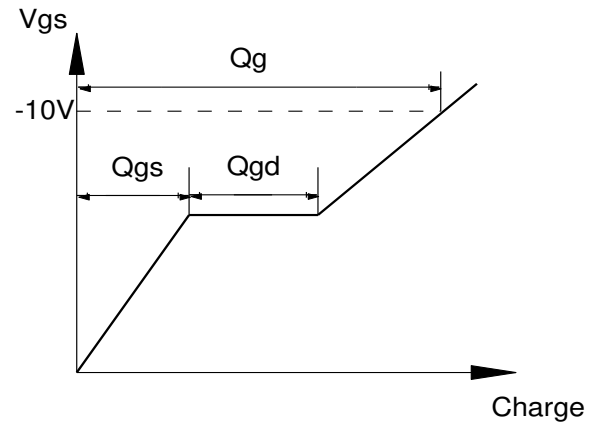
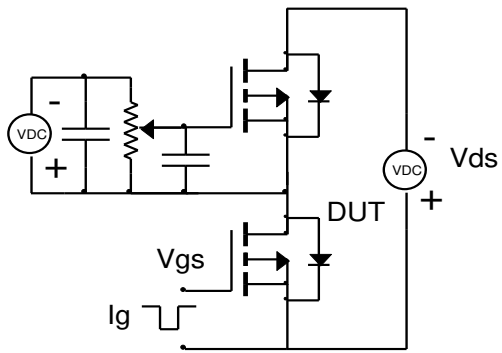
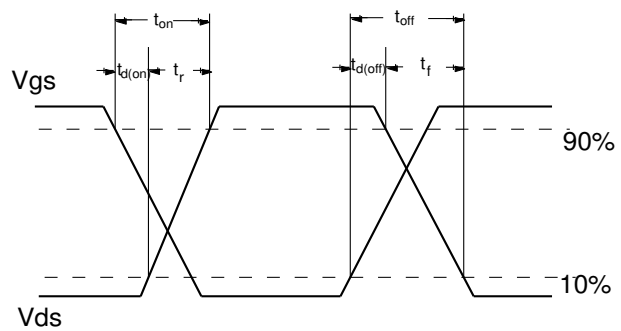
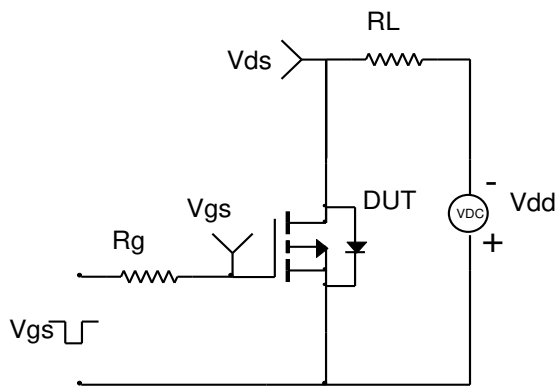


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

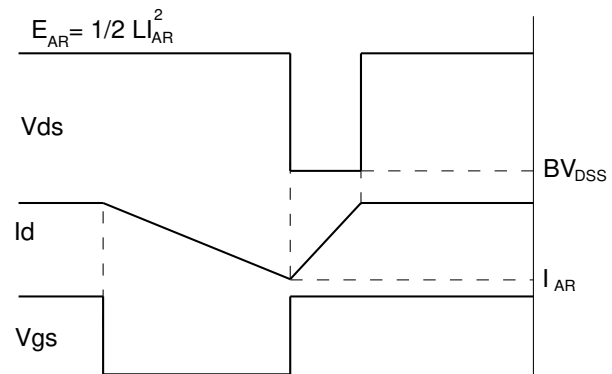
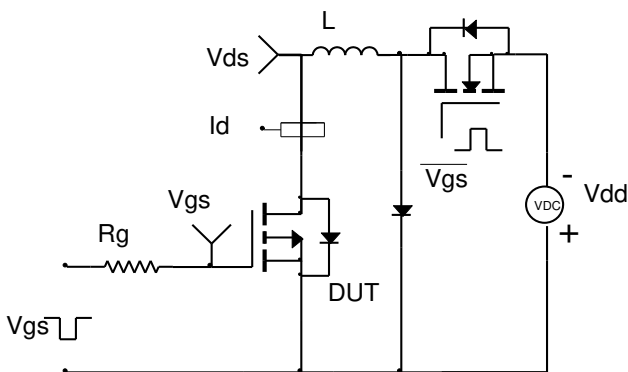
Gate Charge Test Circuit & Waveform



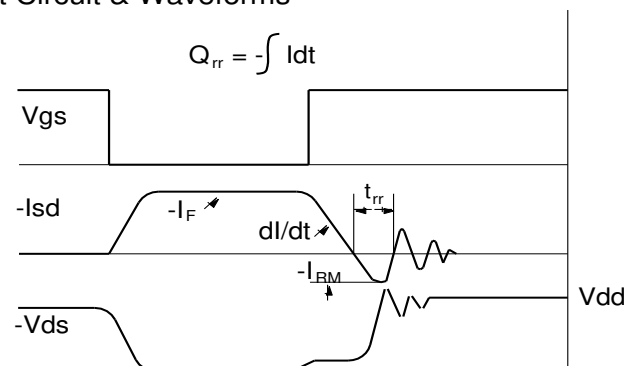
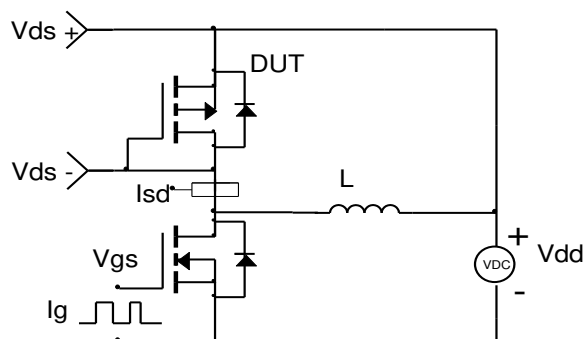
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



N-CH Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0V	30			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =30V, V _{GS} =0V T _J =55°C			1 5	μA
I _{GSS}	Gate-Body leakage current	V _{DS} =0V, V _{GS} =±20V			±10	μA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.3	1.8	2.3	V
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =7A T _J =125°C		16 24	20 30	mΩ
		V _{GS} =4.5V, I _D =6.3A		20	26	mΩ
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =7A		33		S
V _{SD}	Diode Forward Voltage	I _S =1A, V _{GS} =0V		0.7	1	V
I _S	Maximum Body-Diode Continuous Current				2	A
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =15V, f=1MHz		600		pF
C _{oss}	Output Capacitance			70		pF
C _{rss}	Reverse Transfer Capacitance			60		pF
R _g	Gate resistance	f=1MHz	1.2	2.4	3.6	Ω
SWITCHING PARAMETERS						
Q _g (10V)	Total Gate Charge	V _{GS} =10V, V _{DS} =15V, I _D =7A		12	20	nC
Q _g (4.5V)	Total Gate Charge			6	12	nC
Q _{gs}	Gate Source Charge			2.2		nC
Q _{gd}	Gate Drain Charge			2.5		nC
t _{D(on)}	Turn-On DelayTime	V _{GS} =10V, V _{DS} =15V, R _L =2.143Ω, R _{GEN} =3Ω		4.5		ns
t _r	Turn-On Rise Time			4		ns
t _{D(off)}	Turn-Off DelayTime			20		ns
t _f	Turn-Off Fall Time			4		ns
t _{rr}	Body Diode Reverse Recovery Time	I _F =7A, di/dt=500A/μs		5		ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =7A, di/dt=500A/μs		6		nC

A. The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C. The value in any given application depends on the user's specific board design.

B. The power dissipation P_D is based on T_{J(MAX)}=150° C, using ≤ 10s junction-to-ambient thermal resistance.

C. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150° C. Ratings are based on low frequency and duty cycles to keep initial T_J=25° C.

D. The R_{θJA} is the sum of the thermal impedance from junction to lead R_{θJL} and lead to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300μs pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-ambient thermal impedance which is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, assuming a maximum junction temperature of T_{J(MAX)}=150° C. The SOA curve provides a single pulse rating.

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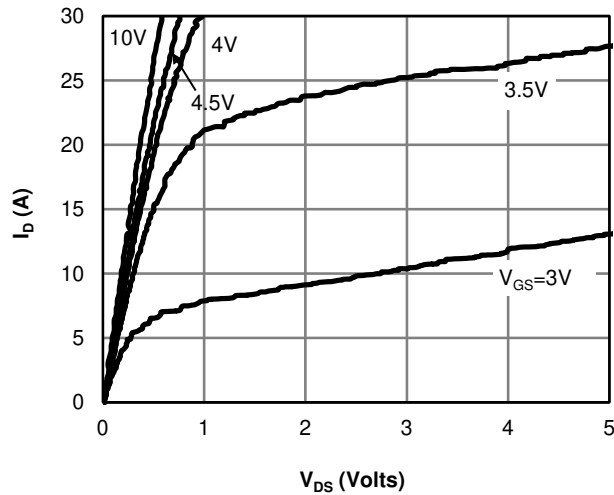


Figure 1: On-Region Characteristics (Note E)

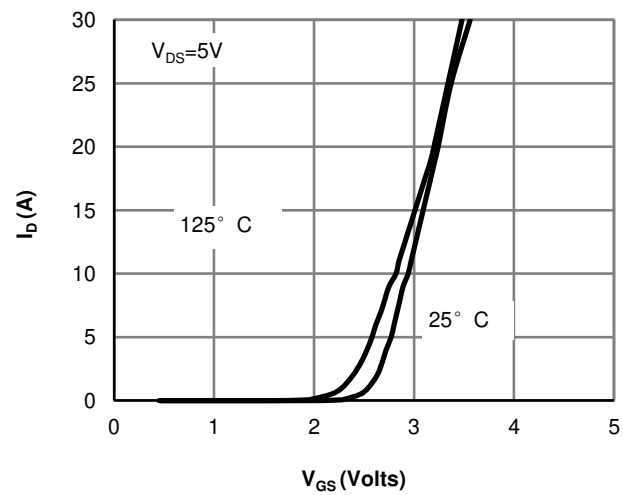


Figure 2: Transfer Characteristics (Note E)

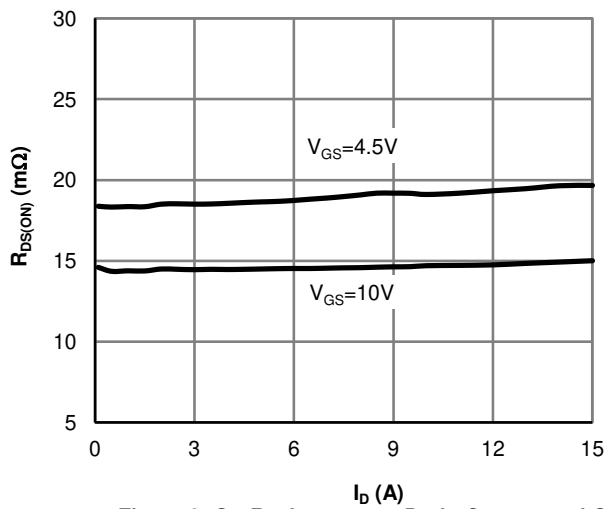


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

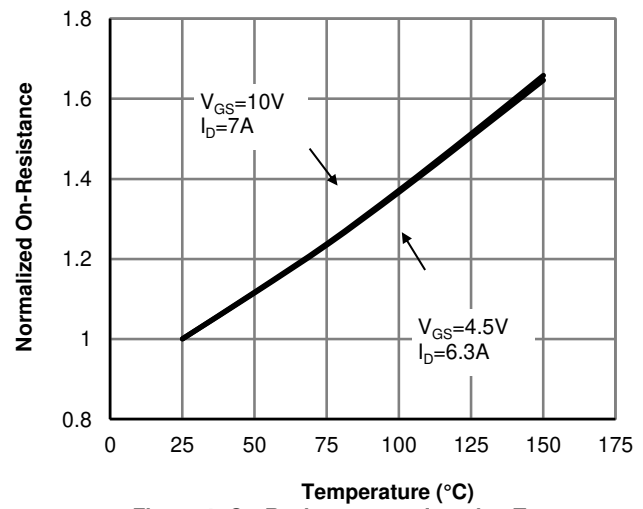


Figure 4: On-Resistance vs. Junction Temperature (Note E)

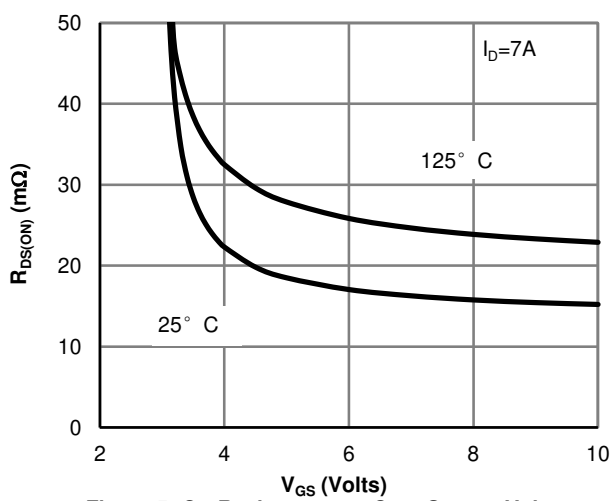


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

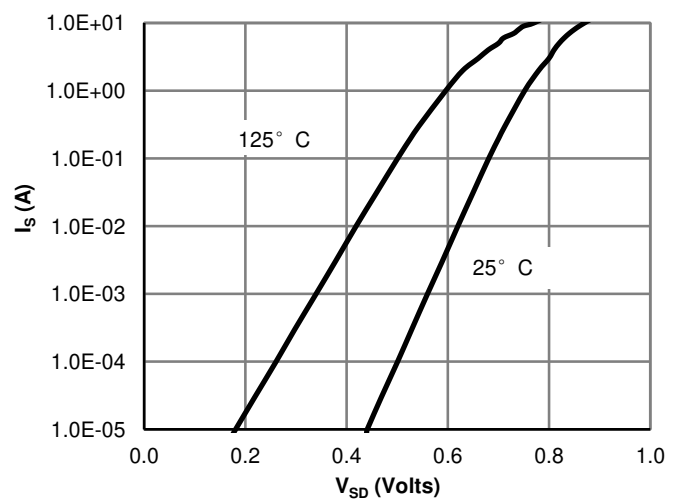


Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

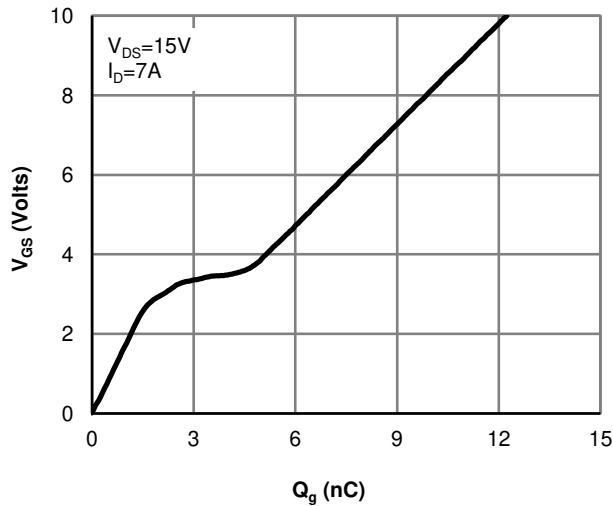


Figure 7: Gate-Charge Characteristics

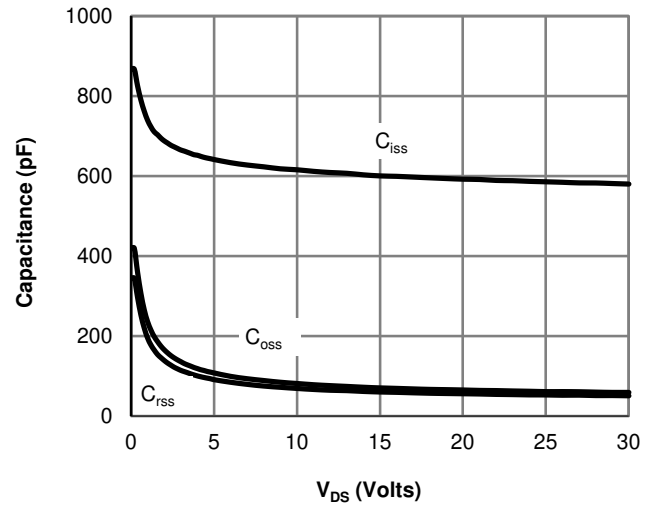


Figure 8: Capacitance Characteristics

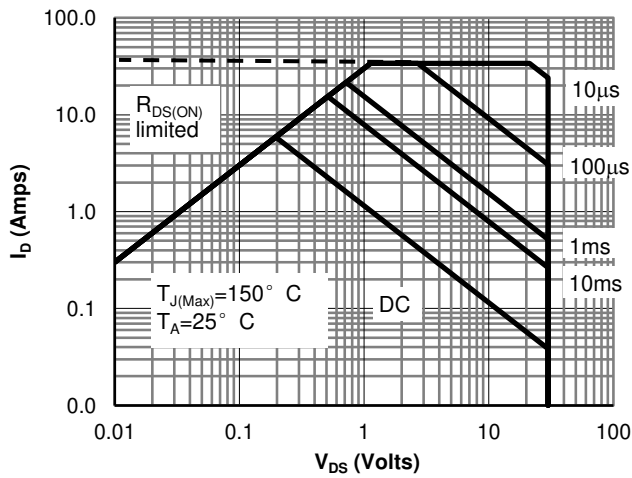


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

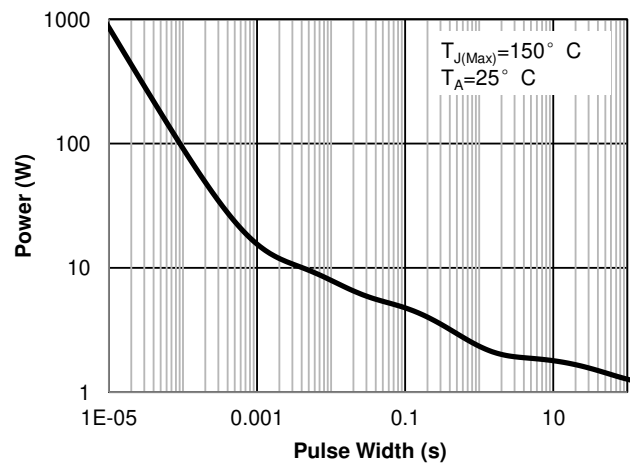


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note F)

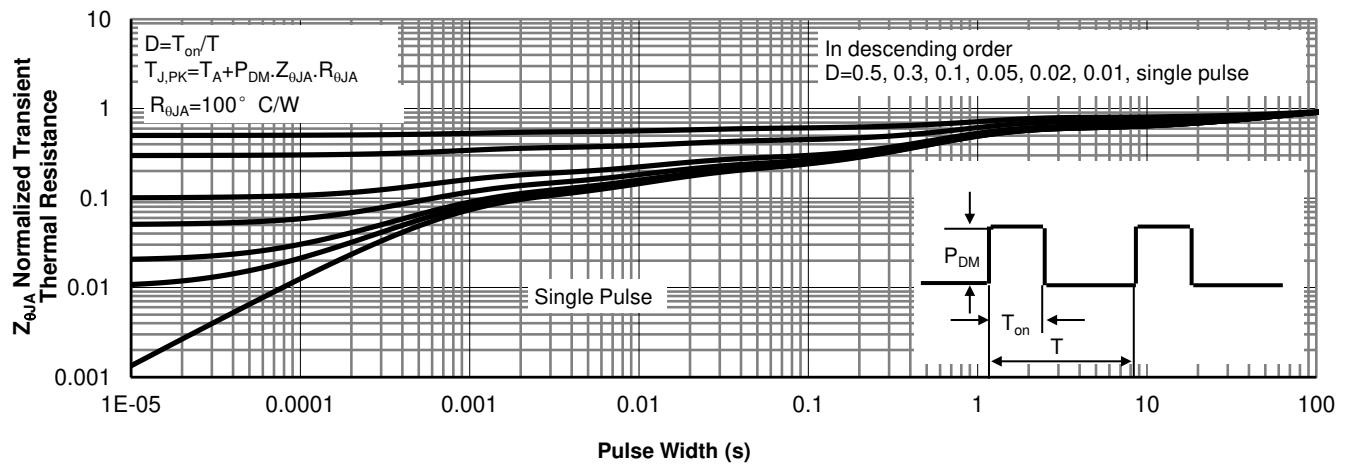


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

Figure A: Gate Charge Test Circuit & Waveforms

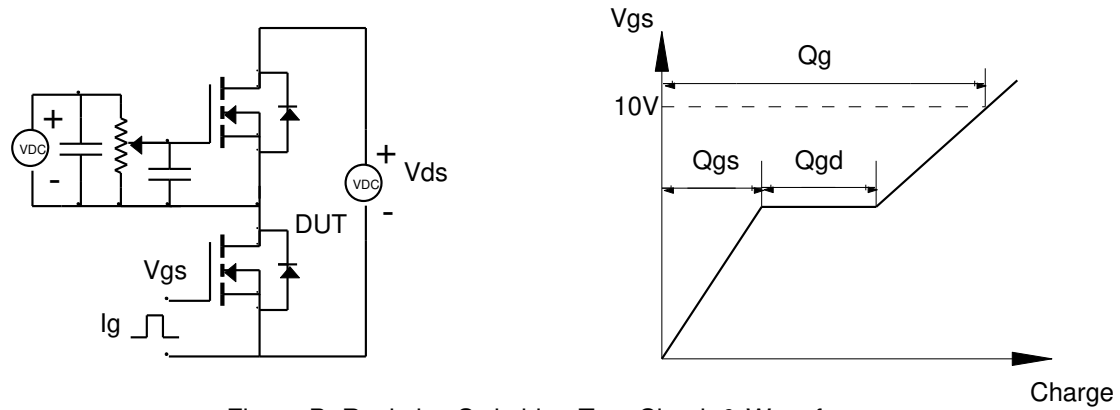


Figure B: Resistive Switching Test Circuit & Waveforms

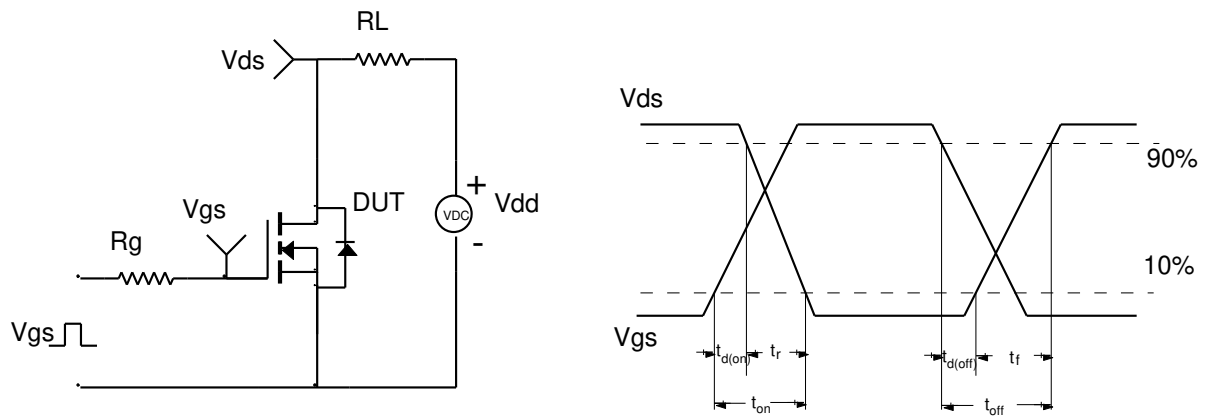


Figure C: Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

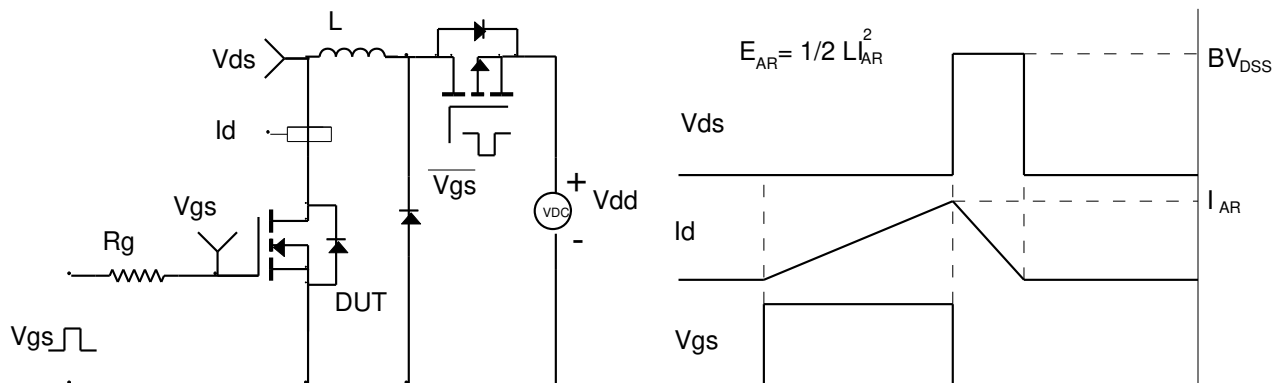


Figure D: Diode Recovery Test Circuit & Waveforms

